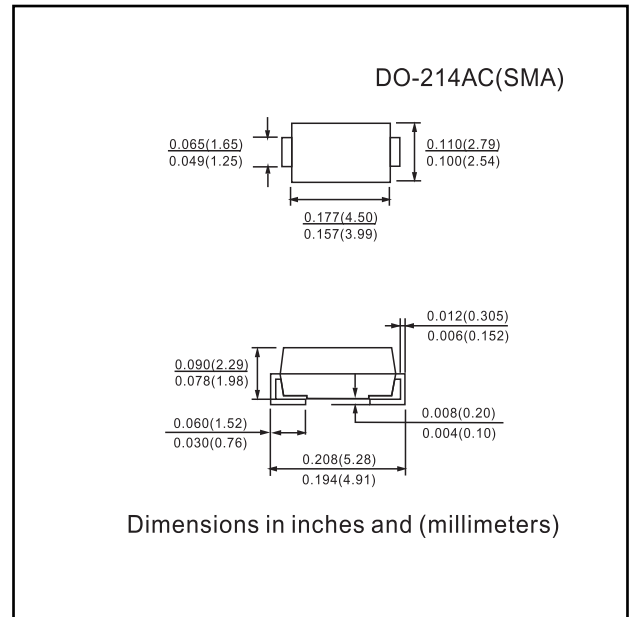


**FEATURES**

- ◆ Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low profile package
- ◆ Built-in strain relief, ideal for automated placement
- ◆ Glass passivated chip junction
- ◆ High temperature soldering: 250°C/10 seconds at terminals

**MECHANICAL DATA**

**Case:** JEDEC DO-214AC molded plastic over passivated chip  
**Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026  
**Polarity:** Color band denotes cathode end  
**Weight:** 0.002 ounce, 0.064 gram



**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Ratings at 25°C ambient temperature unless otherwise specified.

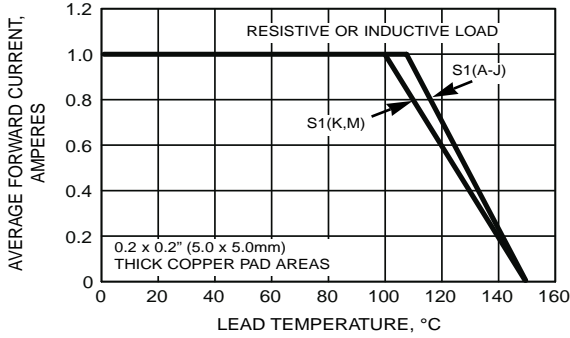
	SYMBOLS	S1A	S1B	S1D	S1G	S1J	S1K	S1M	UNITS
Device marking code		SA	SB	SD	SG	SJ	SK	SM	
Maximum recurrent peak reverse voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	Volts
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	Volts
Maximum DC blocking voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	Volts
Maximum average forward rectified current See Figure 1	I <sub>(AV)</sub>	1.0							Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) T <sub>L</sub> =110°C	I <sub>FSM</sub>	40.0					30.0		Amps
Maximum instantaneous forward voltage at 1.0A	V <sub>F</sub>	1.10							Volts
Maximum DC reverse current at Rated DC blocking voltage	I <sub>R</sub>	1.0					5.0		μA
		50.0							
Typical reverse recovery time (NOTE 1)	t <sub>rr</sub>	1.8							μs
Typical junction capacitance (NOTE 2)	C <sub>J</sub>	12.0							pF
Typical thermal resistance (NOTE 3)	R <sub>θJA</sub>	75.0					85.0		°C/W
	R <sub>θJL</sub>	27.0					30.0		
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150							°C

**NOTES:**

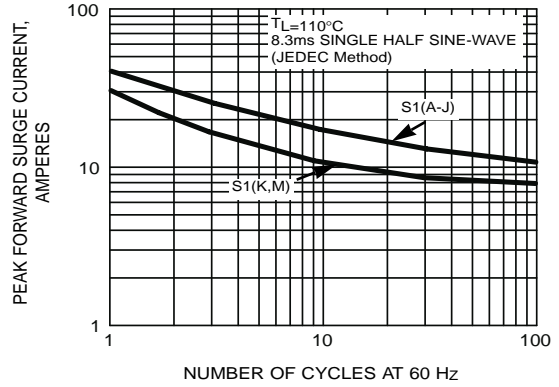
- (1) Reverse recovery test conditions: I<sub>F</sub>=0.5A, I<sub>R</sub>=1.0A, I<sub>rr</sub>=0.25A
- (2) Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts
- (3) Thermal resistance from junction to ambient and from junction to lead mounted on 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas

**RATING AND CHARACTERISTIC CURVES S1A THRU S1M**

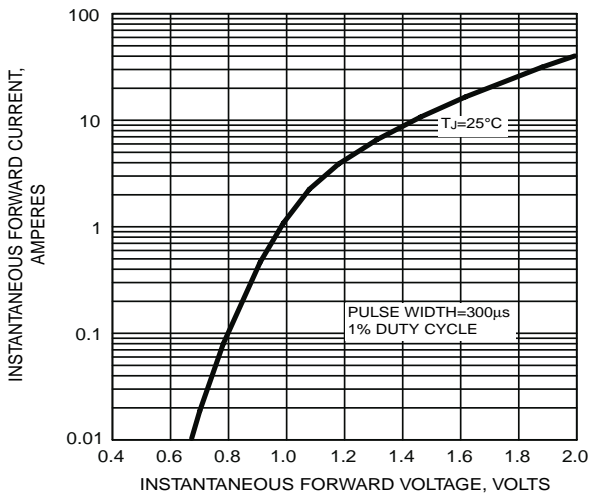
**FIG. 1 - FORWARD CURRENT DERATING CURVE**



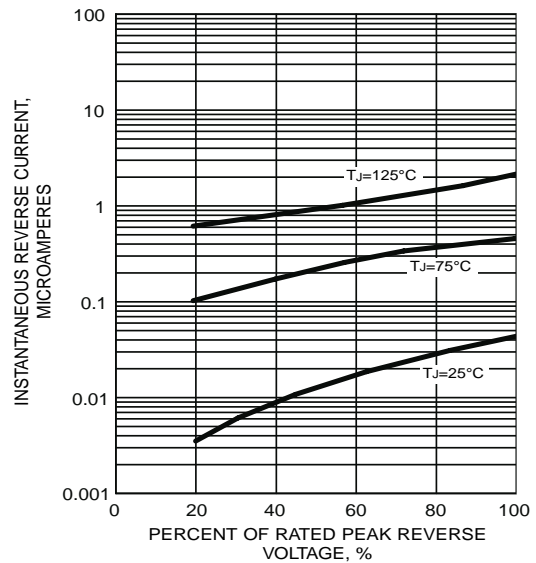
**FIG. 2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT**



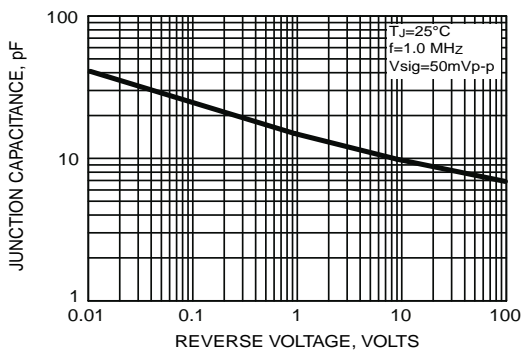
**FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS**



**FIG. 4 - TYPICAL REVERSE CHARACTERISTICS**



**FIG. 5 - TYPICAL JUNCTION CAPACITANCE**



**FIG. 6 - TRANSIENT THERMAL IMPEDANCE**

